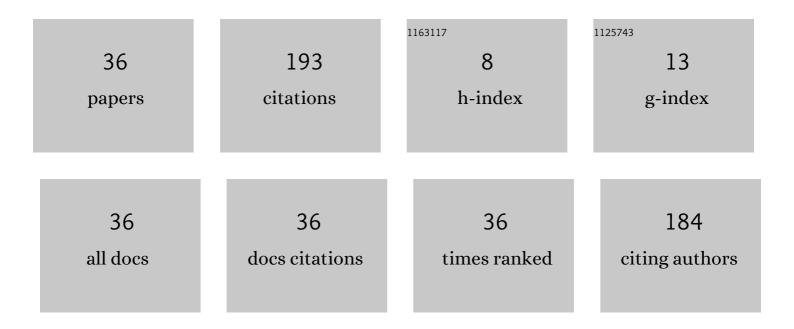
William R Eisenstadt

List of Publications by Year in descending order

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#	Article	IF	CITATIONS
1	Broadband Active Balun Using Combined Cascode–Cascade Configuration. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1790-1796.	4.6	35
2	A New Characterization and Calibration Method for 3-dB-Coupled On-Wafer Measurements. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1193-1200.	4.6	17
3	Wirelessly triggered bioactive molecule delivery from degradable electroactive polymer films. Polymer International, 2021, 70, 467-474.	3.1	17
4	Software Defined Match Control Circuit Integrated With a Planar Inverted F Antenna. IEEE Transactions on Antennas and Propagation, 2010, 58, 3884-3890.	5.1	16
5	Tunable Broadband MMIC Active Directional Coupler. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 168-176.	4.6	16
6	Embedded RF Test Circuits: RF Power Detectors, RF Power Control Circuits, Directional Couplers, and 77-GHz Six-Port Reflectometer. Journal of Information and Communication Convergence Engineering, 2013, 11, 56-61.	0.2	15
7	Marchand Balun Embedded Probe. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1207-1214.	4.6	13
8	CMOS Programmable Gain Distributed Amplifier With 0.5-dB Gain Steps. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 1552-1559.	4.6	13
9	High speed digital CMOS divide-by-N fequency divider. , 2008, , .		8
10	Low-power wireless climate monitoring system with RFID security access feature for mosquito and pathogen research. , 2015, , .		7
11	Integrated BiCMOS 10 GHz S-Parameter Module. Bipolar/BiCMOS Circuits and Technology Meeting, IEEE Proceedings of the, 2006, , .	0.0	4
12	Evaluation of Measurement Uncertainties Caused by Common and Cross Modes in Differential Measurements Using Baluns. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1485-1492.	4.6	4
13	High speed I/O and thermal effect characterization of 3D stacked ICs. , 2009, , .		4
14	Automated wideband test system, measurement uncertainty, and design of on-chip six-port reflectometers for 5G applications. , 2015, , .		4
15	Testing and Validation of Adaptive Impedance Matching System for Broadband Antenna. Electronics (Switzerland), 2019, 8, 1055.	3.1	3
16	A wide-band differential and single-ended microwave amplitude detector. , 2010, , .		2
17	GTL high speed I/O in 3D ICs for TSV and interconnect signal integrity characterization. , 2012, , .		2
18	Design and packaging of small 60 GHz antenna array for multi-chip communication. , 2012, , .		2

#	Article	IF	CITATIONS
19	CMOS Broadband Programmable Gain Active Balun With 0.5-dB Gain Steps. IEEE Transactions on Microwave Theory and Techniques, 2015, 63, 2650-2660.	4.6	2
20	IIP <inf>3</inf> estimation from gain compression of RF power amplifiers. , 2005, , .		1
21	A low-power CAM using a 12-transistor design cell. , 2007, , .		1
22	Design of Multigigabit-per-Second Transceiver for Band-Limited High-Speed Data Communication Using DC-Free Signaling. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1555-1564.	4.6	1
23	On-chip S <inf>11</inf> signal detection circuit. , 2009, , .		1
24	A sub-1V CMOS voltage reference generator. , 2011, , .		1
25	Polarization Differential Antenna for LOS Communications in a Multi-Antenna System. IEEE Transactions on Antennas and Propagation, 2014, 62, 3978-3984.	5.1	1
26	A 6 pJ/bit transmitter front end in 130 nm CMOS technology for wireless interconnect. , 2015, , .		1
27	Progress in development of the low-power wireless multiple temperature sensor pole for pesticide, agriculture, and mosquito research. , 2015, , .		1
28	Guest Editorial: Analog, Mixed-Signal and RF Testing. Journal of Electronic Testing: Theory and Applications (JETTA), 2017, 33, 281-282.	1.2	1
29	Role of Silver Doping in the Improvement of Electrical Properties of (Ba,Sr)TiO3 Thin Films. Materials Research Society Symposia Proceedings, 1999, 567, 463.	0.1	0
30	Embedded Jitter Measurement of High-speed I/O Signals. , 2007, , .		0
31	Design of compact adaptive RF matching circuits using Square split ring resonators. , 2010, , .		О
32	Signal integrity characterization of high-speed I/O in 3D chip-package system. , 2013, , .		0
33	Characterization of embedded RF elements on a 3D integrated circuit. , 2013, , .		0
34	Cost effective modeling methodologies and evaluating electrical interaction in FCBGA packages. , 2013, , .		0
35	True-differential/common-mode mixed-mode S-parameter measurement techniques for cellular and 4G bandwidths. , 2015, , .		0
36	Structural parameters effect on signal integrity of inter-tier vias in 3D stacking technology. , 2018, , .		0

Structural parameters effect on signal integrity of inter-tier vias in 3D stacking technology. , 2018, , . 36